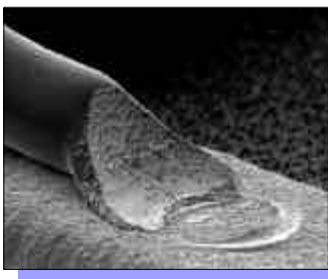


## 绝缘纳米涂层键合线产品参数

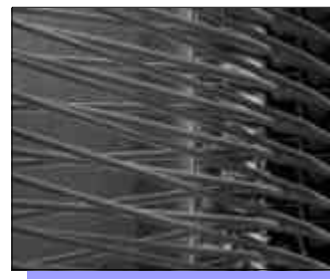
Insulation Coated Bonding Wire Product Parameters



Free Air Ball



Stitch Bond



Crossing Wires

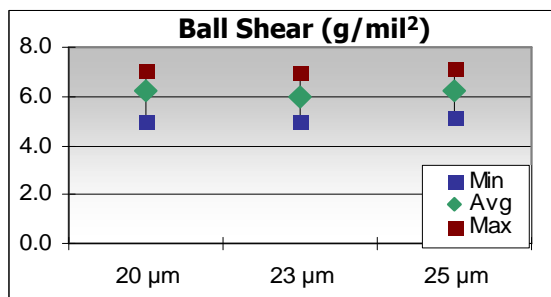
### Insulation Coated Bonding Wire Product Parameters Target Applications

- ▶ Stack Die
- ▶ Multi-Row ICs
- ▶ Yield Improvement
- ▶ Engineering Changes
- ▶ Die Shrink
- ▶ Substrate Reduction

### Performance Data

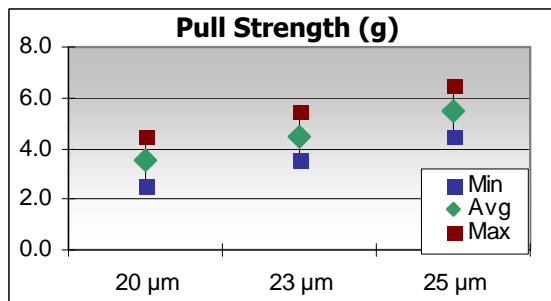
#### Ball Bond

- ▶ Good Ball Shear Strength
- ▶ No Capillary Build Up
- ▶ Small FAB Capability



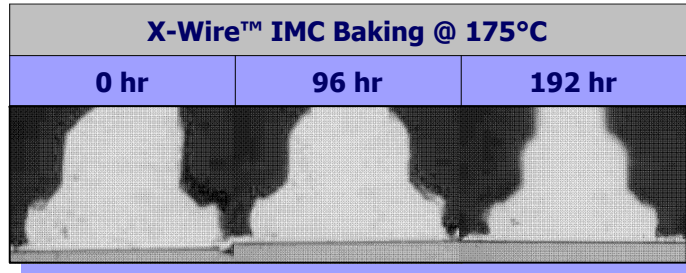
#### Stitch Bond

- ▶ Good Pull Strength
- ▶ Laminate & Leadframe
- ▶ Reverse Stitch Bonding



### IMC

- ▶ Good IMC Coverage
- ▶ Passed 192 hr @ 175°C
- ▶ Comparable to Bare Wire



### Reliability

- ▶ MSL 3 – Pre-Condition
- ▶ Biased HAST (**HAST/B**):
  - ▶ 130°C, 85 RH, 4 V, 100 hr
- ▶ High Temp. Storage (**HTS**)
  - ▶ 150°C, 1500 hr
- ▶ Thermal Cycle (**T/C**)
  - ▶ -55 to 125°C, 1000 cycle

X-Wire™ Reliability Test Summary			
BGA 503	HAST/B	HTS	T/C
Lot 1	45/45 pass	45/45 pass	45/45 pass
Lot 2	45/45 pass	45/45 pass	45/45 pass
Lot 3	45/45 pass	45/45 pass	45/45 pass

### Additional Features

- ▶ Excellent Coating Adhesion
- ▶ High Temperature & Lead-Free Compatible

## Insulation coated bonding wires Start Kit

To Order Please Contact

### Wire Diameter

- ▶ 20 μm, 23 μm & 25 μm
- ▶ 200 m Sample Spools
- ▶ Bare Wire from Tanaka

### Wire Bonder Kit

- ▶ ASM Eagle & K&S Maxum Platform
- ▶ Capillaries

### Documentation on CD-ROM

- ▶ Wire Bonder Setup Instructions
- ▶ Process Parameters & Wire Bond Design Rules



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